PREFACE

Dear Distinguished Delegates and Guests,

The 3rd International Conference on Computer-Aided Design, Manufacturing, Modeling and Simulation (CDMMS2013) was held in Chongqing, China, from September 21-23, 2013, serving as a platform for expertise exchange. CDMMS2013 had drawn the attention of researchers from various disciplines: CAD, CAM, Manufacturing, Mechanical Engineering, Modeling and simulation, etc.

Persons who attended the conference were engineers, scientists, managers of various companies and professors of the universities abroad and home. We have had record number of submission 532 this year. From which 151 papers have been accepted for presentation at the conference and will be published by TTP, in Applied Mechanics and Materials (AMM) Journal (ISSN: 1660-9336), which is online available in full text via the platform www.scientific.net. AMM should be indexed by EI according the previous TTP index results.

We express our special gratitude to all the members of the General Committee Chairs, Program Committee Chairs, Technical Program Committee and Steering Committee who worked so hard to prepare the conference and who supported the conference so professionally.

The 3rd International Conference on Computer-Aided Design, Manufacturing, Modeling and Simulation (CDMMS2013) is organized by Hunan Institute of Engineering, Zhejiang Gongshang University, Nanyang Technological University, Shanghai Jiao Tong University, Beijing University, and sponsored by National Natural Science Foundation of China (NSFC), Provincial Natural Science Foundation of Hunan (13JJ9022), Provincial Science & Technology plan project of Hunan(2013GK3029). Their kind support makes CDMMS2013 become possible. Especially, we should thank the TTP.

Finally, we would like to thanks all the authors, speakers and participants of this conference for taking part in and contributing to the International Conference on Computer-Aided Design, Manufacturing, Modeling and Simulation.

We hope you have a unique, rewarding and enjoyable week at CDMMS2013 in Chongqing.

With our warmest regards,

CDMMS2013 Organizing Committees
September 21-23, 2013
Chongqing, China

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